



Title of Change:	Mask Design Change of NSVMMBT6520LT1G for Product Robustness.
Proposed Changed Material First Ship Date:	13 April 2018 <i>or earlier upon customer approval</i>
Current Material Last Order Date:	15 December 2016 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.
Current Material Last Delivery Date:	30 December 2016 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.
Product Category:	<i>Active components – Discrete components</i>
Contact information	Contact your local ON Semiconductor Sales Office or Coleen.Long@onsemi.com
Samples	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.
Sample Availability Date:	30 March 2018
PPAP Availability Date:	30 March 2018
Additional Reliability Data	Contact your local ON Semiconductor Sales Office or Laura.Rivers@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category:	Type of Change
Design	Mask Design Change
Description and Purpose: ON Semiconductor is notifying customers of ISMF fabrication facility (Seremban, Malaysia) to perform mask design change that are compatible in order to meet ON Semiconductor quality requirements. The ISMF Fab facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor that is TS16949, ISO-9001 and ISO-14000 certified. Qualification tests are designed to show that the reliability of the device will continue to meet or exceed ON Semiconductor standards.	
Reason / Motivation for Change:	Product robustness: Modify the die layout to include a base metal overlay that covers the entire base perimeter. Base metal overlay is expected to widen the depletion region producing a higher BVCBO with a lower electrical field.
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

